

**IN THE DRAWINGS:**

The attached Drawings include changes to Figs. 2, 4A, 5A and 10C. The changed drawings eliminate the cross hatching on figures that do not show cross sections.

Pursuant to statutory requirements, each sheet containing the changed Drawings is labeled "Replacement Sheet" in the top margin

## REMARKS

### STATUS OF THE CLAIMS

In accordance with the foregoing, the Specification and claim 1 have been amended and claim 5 has been cancelled. New claim 8 has been added. Claims 1, 2 and 8 are pending and under consideration.

No new matter is being presented, and approval and entry of amended and new claims are respectfully requested.

### CHANGES TO THE ABSTRACT

On page 3, item 4, of the Office Action, the Examiner objects to the Abstract because of the presence of legal phraseology.

The Abstract is amended herein to eliminate the legal phraseology. Therefore, it is respectfully submitted that the objection is overcome. Approval of the amended Abstract is respectfully requested.

### CHANGES TO THE DRAWINGS

In the Office Action, at item 3, the Examiner objects to the Drawings as being improperly cross hatched. In order to overcome these objections, replacement sheets for Figs. 2, 4A, 5A and 10C are submitted herewith.

Figs. 2, 4A, 5A and 10C have been changed to eliminate the improper cross hatching. The sheets containing these figures have been labeled in the top margin with "Replacement Sheet". Approval of these changes to the Drawings is respectfully requested.

### CHANGES TO THE SPECIFICATION

On page 3, item 5, of the Office Action, the Examiner objects to paragraph [0017] since "substrate 22" should read "substrate 26".

Paragraph [0017] is amended herein to correct the informality and, thus, the objection is respectfully overcome. Approval of the amended Specification is respectfully requested.

REJECTIONS OF CLAIMS 1, 2 AND 5 UNDER 35 U.S.C. §102(b) AS BEING ANTICIPATED BY TESSIER ET AL. (U.S. PATENT NO. 5,789,815)

The rejections of claims 1, 2 and 5 are respectfully traversed and reconsideration is requested.

The housing preform, as recited in amended claim 1, is comprised of a bendable plate member having a monolithic flat form in the shape of an unfolded 3D housing. Electronic components and interconnects electrically connecting the electronic components are formed on the bendable plate member and inside the housing when the bendable plate member is bent to form the housing.

Simply folding the housing preform recited in claim 1 immediately produces a housing with an electronic circuit mounted therein.

In contrast, Tessier et al. (hereinafter "Tessier") merely teaches a semiconductor package formed by sealing semiconductor chips connected with a flexible board, which has no relationship with the housing preform of the present invention, which is formed in a monolithic flat form in the shape of an unfolded 3D housing. (See Fig. 1 of Tessier).

In fact, in Tessier, a protective cap 62 is added on top of the folded flexible boards. (See Fig. 5 and column 5, lines 1-3). Because of the shape of the housing preform, as recited in amended claim 1, no additional protective cap is necessary.

Therefore, it is respectfully submitted that amended claim 1 patentably distinguishes over the reference. Claim 2 depends from claim 1 and inherits its patentable recitations. Thus, it is respectfully submitted that claim 2 patentably distinguishes over the reference.

REJECTIONS OF CLAIMS 1, 2 AND 5 UNDER 35 U.S.C. §102(b) AS BEING ANTICIPATED BY VU ET AL. (U.S. PATENT NO. 6,027,958)

The rejections of claims 1, 2 and 5 are respectfully traversed and reconsideration is requested.

Vu et al. (hereinafter "Vu") merely discloses a flexible board, with active devices mounted thereon, that is foldable along an arc. (See Fig. 11 and column 9, lines 24-39). However, Vu has no relation to a housing preform comprised of a bendable plate member, in a shape of an unfolded and flat housing, so that the housing preform is bendable to form the housing, inside of which electronic components and interconnects electrically connecting said electronic

components are formed on the bendable plate member, as recited in amended claim 1.

Therefore, it is respectfully submitted that amended claim 1 patentably distinguishes over Vu. Claim 2 depends from claim 1 and inherits its patentable recitations. Thus, it is respectfully submitted that claim 2 patentably distinguishes over the reference.

#### NEW INDEPENDENT CLAIM 8

New claim 8 recites:

a bendable plate member, in a two-dimensional configuration, having a base and panels integral with the base, about bend lines defining a perimeter of the base, and the panels, when bent, being commonly erected and interconnecting sidewalls relating to the base and together, with the base, forming the housing, and electronic components and interconnects electrically connecting said electronic components being formed, on the base and panels.

Neither Tessier nor Vu teaches or suggests these features. Therefore, it is respectfully submitted that claim 8 is patentable over the references.

#### CONCLUSION

In accordance with the foregoing, it is respectfully submitted that all outstanding objections and rejections have been overcome and/or rendered moot. Further, all pending claims patentably distinguish over the prior art. There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.

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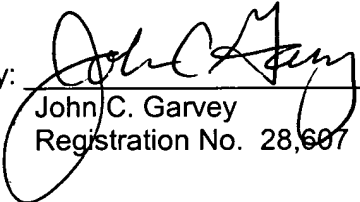
Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

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